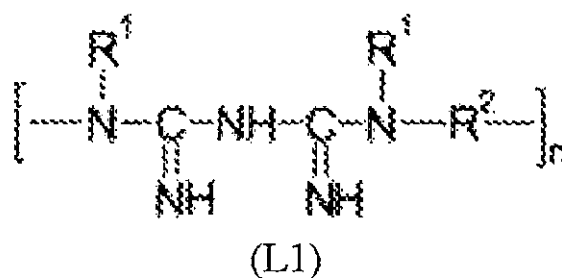


ABSTRACT**COMPOSITION FOR METAL ELECTROPLATING COMPRISING LEVELING AGENT**

Disclosed is a composition comprising a source of metal ions, one or more suppressing agents and at least one additive comprising a linear or branched, polymeric biguanide compound comprising the structural unit of formula L1 or the corresponding salt thereof, wherein R^1 is independently selected from H or an organic radical having 1-20 carbon atoms; R^2 is an divalent organic radical having 1-20 carbon atoms, optionally comprising 20 polymeric biguanide side branches; and n is an integer of 2 or more.



(No suitable figure)